SLOVENSKI STANDARD
SIST EN 60249-2-8:1997/A1:1997

01-avgust-1997

Base materials for printed circuits - Part 2: Specifications - Specification No.8: Flexible copper-clad polyester (PETP) film (IEC 249-2-8:1987/A1:1987) - Amendment 1

Base materials for printed circuits -- Part 2: Specifications -- Specification No. 8: Flexible copper-clad polyester (PETP) film

Basismaterialien für gedruckte Schaltungen -- Teil 2: Einzelbestimmungen -- Einzelbestimmung Nr. 8: Flexible kupferkaschierte Polyester- (PETP-) Folie

Matériaux de base pour circuits imprimés -- Partie 2: Spécifications -- Spécification n° 8: Film flexible de polyester (PETP) recouvert de cuivre

Ta slovenski standard je istoveten z: **EN 60249-2-8:1994/A1:1994**

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards

SIST EN 60249-2-8:1997/A1:1997 **en**

EUROPEAN STANDARD EN 60249-2-8/A1

NORME EUROPEENNE

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UDC 621.3.049.75-036.744

Descriptors: Printed circuit, composite materials, polyester, copper

Amendment A1 to the English version of EN 60249-2-8

Base materials for printed circuits
Part 2: Specifications
Specification No. 8: Flexible copper-clad polyester (PETP) film
(IEC 249-2-8:1987/A1:1993)

Matériaux de base pour circuits imprimés
Partie 2: Spécifications
Spécification n° 8: Film flexible de polyester (PETP) recouvert de cuivre
(CEI 249-2-8:1987/A1:1993)

Basismaterialien für gedruckte Schaltungen
Teil 2: Einzelbestimmungen
Einzelbestimmung Nr. 8: Flexible kupferkaschierte Polyester-(PETP-)Folie
(IEC 249-2-8:1987/A1:1993)

This amendment A1 modifies the European Standard EN 60249-2-8:1994. It was approved by CENELEC on 1993-12-08. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this amendment the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This amendment exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B-1050 Brussels

FOREWORD

At the request of the 76th Technical Board of CENELEC, amendment 1:1993 to the International Standard IEC 249-2-8:1987 was submitted to the CENELEC members for formal vote.

The text of the International Standard was approved by CENELEC as amendment A1 to EN 60249-2-8 on 8 December 1993.

The following dates were fixed:

- latest date of publication of an identical national standard	(dop)	1995-03-15
- latest date of withdrawal of conflicting national standards	(dow)	1995-03-15

ENDORSEMENT NOTICE

The text of amendment 1:1993 to the International Standard IEC 249-2-8:1987 was approved by CENELEC as an amendment to the European Standard without any modification.

NORME INTERNATIONALE
INTERNATIONAL STANDARD

CEI
IEC
249-2-8

1987

AMENDEMENT 1
AMENDMENT 1

1993-05

Amendement 1

Matériaux de base pour circuits imprimés

Partie 2: Spécifications
Spécification n° 8: Film flexible de polyester (PETP) recouvert de cuivre

Amendment 1

Base materials for printed circuits

Part 2: Specifications
Specification No. 8: Flexible copper-clad polyester (PETP) film

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Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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FOREWORD

This amendment has been prepared by IEC technical committee No. 52: Printed circuits.

The text of this amendment is based on the following documents:

DIS	Reports on Voting
52(CO)378	52(CO)387
52(CO)379	52(CO)388
52(CO)380	52(CO)389
52(CO)391	52(CO)395

Full information on the voting for the approval of this amendment can be found in the reports on voting indicated in the above table.

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4 Electrical properties, table III

Replace the present property designation by:

Surface resistance after damp heat while in the humidity chamber (optional)

Surface resistance after damp heat and recovery

Volume resistivity after damp heat while in the humidity chamber (optional)

Volume resistivity after damp heat and recovery

Page 15, table VI

Replace table VI as follows:

Property	Test method (Subclause of IEC 249-1)	Requirements		
		Thickness of the copper foil		
		18 µm*	35 µm*	70 µm*
Peel strength as received	3.6	Not less than 0,5 N/mm (2,9 lbf/in)	Not less than 0,7 N/mm (4,0 lbf/in)	Not less than 0,9 N/mm (5,1 lbf/in)
Peel strength after dry heat for 30 min at 125 °C (optional)	3.6.3	Not less than 0,5 N/mm (2,9 lbf/in)	Not less than 0,7 N/mm (4,0 lbf/in)	Not less than 0,9 N/mm (5,1 lbf/in)
		No blistering nor delamination		
Peel strength after dry heat for 500 h at 100 °C (optional)	3.6.3	Not less than 0,5 N/mm (2,9 lbf/in)	Not less than 0,7 N/mm (4,0 lbf/in)	Not less than 0,9 N/mm (5,1 lbf/in)
		No blistering nor delamination		
Retention of peel strength after immersion in solvent	3.6.6	Not less than 75 % of the previous values. No blistering nor delamination		
Retention of peel strength after simulated plating (optional)	3.6.5	Not less than 75 % of the previous values. No blistering nor delamination		

* 18 µm (152 g/m^2, 0,5 oz/ft^2); 35 µm (305 g/m^2, 1 oz/ft^2); 70 µm (610 g/m^2, 2 oz/ft^2).

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5.6 *Solderability*

Delete the title and text of 5.6.

5.7 *Dimensional stability*

Replace the present table VIII by:

Table VIII – Dimensional stability

Property	Test method (subclause of IEC 249-1)	Requirements
Dimensional stability	3.11 T = (125 ± 2) °C	Under consideration